

Design Concepts For A Total Integrated Solution

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SOUTHWEST TEST WORKSHOP

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DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

DESIGN

PROJECT MANAGEMENT

INTEGRATION



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June 3, 1997*

DESIGN

SYSTEM DESIGN

» CUSTOMER INITIATIVE - CONCEPT SPECIFICATION

» SYSTEM PERFORMANCE

SINGLE SPECIFICATION

Pulse Rise Time

Round Trip Delay

System Impedance

System Capacitance

Bandwidth

RESPONSIBILITY OF SUPPLIER



DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

SYSTEM DESIGN » COMMUNICATION



INTERFACE PROJECT

CERPROBE

PROBER COMPANY

TESTER COMPANY

MANIPULATOR COMPANY

INTERFACE PROJECT

CUSTOMER

LOAD BOARD MFG.

POGO STACK MFG.

PROBE CARD MFG.

PROBER COMPANY

TESTER COMPANY

MANIPULATOR COMPANY



SIGNAL TRANSMISSION

» SYSTEM PERFORMANCE SPEC DRIVES DESIGN

□ CONTROL IMPEDANCE

- **Maintain constant width lines**
- **Maintain constant distance from signal path to reference path or plane**
- **Minimize vias and other discontinuities in the line**
- **Relieve ground planes around those necessary vias**
- **Provide a ground current return path of same length as signal path**



SIGNAL TRANSMISSION

» SYSTEM PERFORMANCE SPEC DRIVES DESIGN

□ MINIMIZE CROSSTALK

- Reference signal lines to low inductance ground plane
- Maximize the distance between lines-maintain minimum of 2.5X dielectric
- Separate critical paths on to separate layers
- Place well grounded guards on either side of more critical lines as shields
- Separate analog and digital grounds
- Where necessary, route signals over fully shielded lines such as semi-rigid coax



SIGNAL TRANSMISSION

» SYSTEM PERFORMANCE SPEC DRIVES DESIGN

MINIMIZE GROUND BOUNCE

- Provide low inductance power and ground planes
- Provide sites for bypass capacitors close to the DUT
- Tie ground lines on top and bottom surfaces to the ground plane at frequent intervals
- Isolate AC signals from critical areas of the board using inductors, in those cases where both areas need to be at the same DC level.



DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

SIGNAL TRANSMISSION

» **START AT THE BOTTOM - WORK UP**

- PROBE CARD**
- POGO STACK**
- PERFORMANCE BOARD**



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SIGNAL TRANSMISSION

» START AT THE BOTTOM - WORK UP

- PROBE CARD**

- The DUT drives the design**

- Size of DUT**

- Parallel testing**

- Direction of array**

- Tester site layout**

- Area for device mounting**



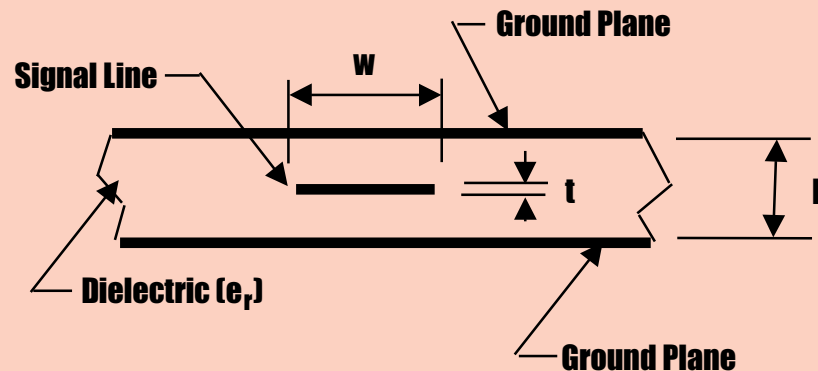
SIGNAL TRANSMISSION

» **START AT THE BOTTOM - WORK UP**

□ **PROBE CARD**

□ **Stripline**

- **Efficient for frequencies up to 4-5 GHz**
- **Can increase layer count**



$$Z_0 = \frac{60}{\sqrt{\epsilon_r}} \ln \left(\frac{4h}{0.67\pi w (0.8 + t/w)} \right)$$



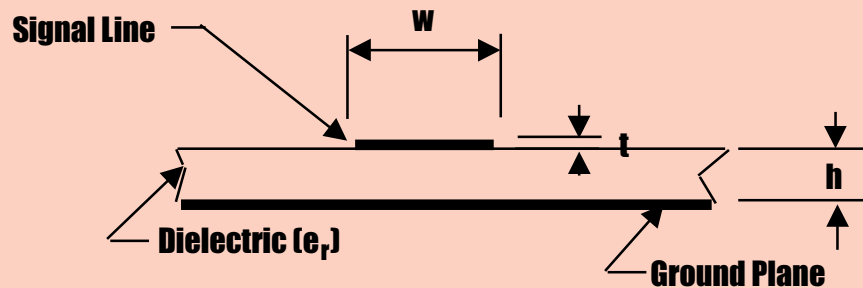
SIGNAL TRANSMISSION

» **START AT THE BOTTOM - WORK UP**

□ PROBE CARD

□ Microstrip

- Efficient for frequencies up to 2-3 GHz
- Easy to add matching resistors or other components to the signal path



$$Z_0 = \frac{87}{\sqrt{\epsilon_r + 1.41}} \ln \left(\frac{5.98h}{0.8w + t} \right)$$



SIGNAL TRANSMISSION

» START AT THE BOTTOM - WORK UP

- PROBE CARD

- Combination

- Watch out for the difference in propagation delay
- Adjust physical line lengths to equalize electrical line lengths and minimize signal skew



SIGNAL TRANSMISSION

» START AT THE BOTTOM - WORK UP

- POGO STACK**

- Choosing the pogo pattern**

- Two wire array**

- Co-planar array**

- 5 wire array**

- Coaxial**

- Isolate signals**

- Isolate signal grounds from power grounds**

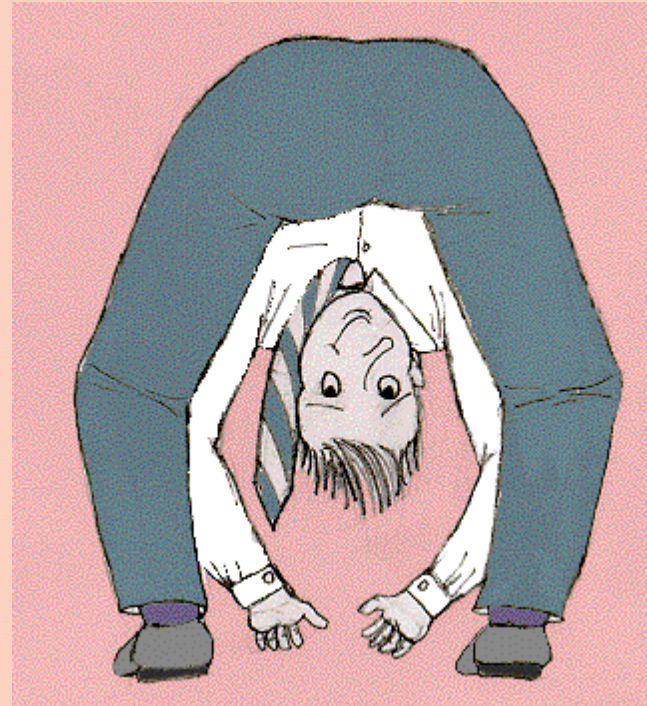


SIGNAL TRANSMISSION

» BOTTOMS UP

PERFORMANCE BOARD

- Translation
 - Tester Pin Out Pattern
 - Probe Card/Pogo Pattern
- Equal Line Length
- Device Population
- Connector City



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MECHANICAL DESIGN

» PCC vs. NON-PCC METHODOLOGY

» PCC

- Probe card/ carrier**
- Pogo stack/ adapter (or insert) ring**
- Load board/ stiffener**
- Docking**



MECHANICAL DESIGN

» PCC vs. NON-PCC METHODOLOGY

» Non-PCC

- Probe card/ stiffener**
- Pogo stack**
- Insert/ clamp ring assembly**
- Load board/ stiffener**
- Docking**



DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

MECHANICAL DESIGN

» LAYOUT ISSUES

Z-Stack

Communicate docking requirements

Communicate PCC issues to proper company

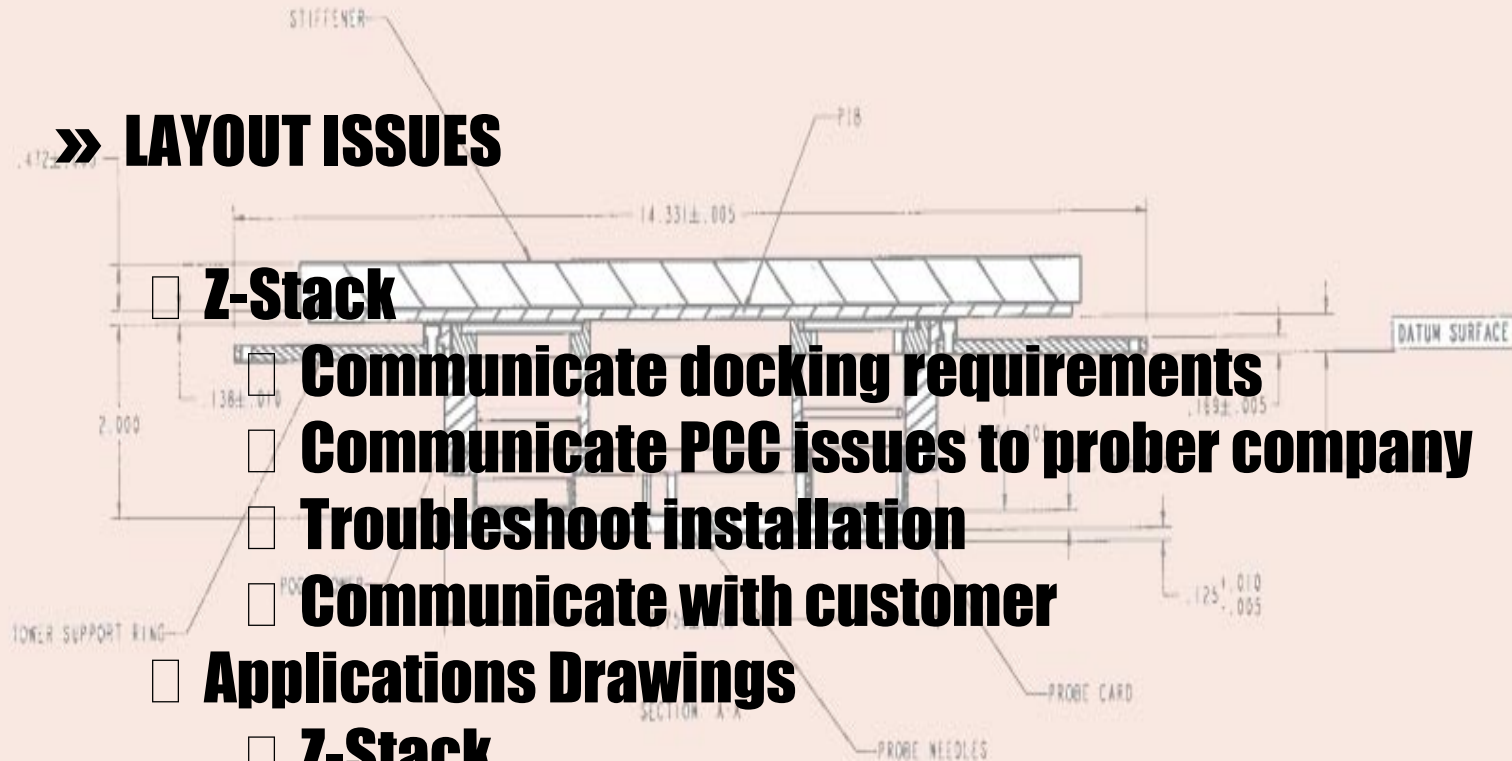
Troubleshoot installation

Communicate with customer

Applications Drawings

Z-Stack

Outline



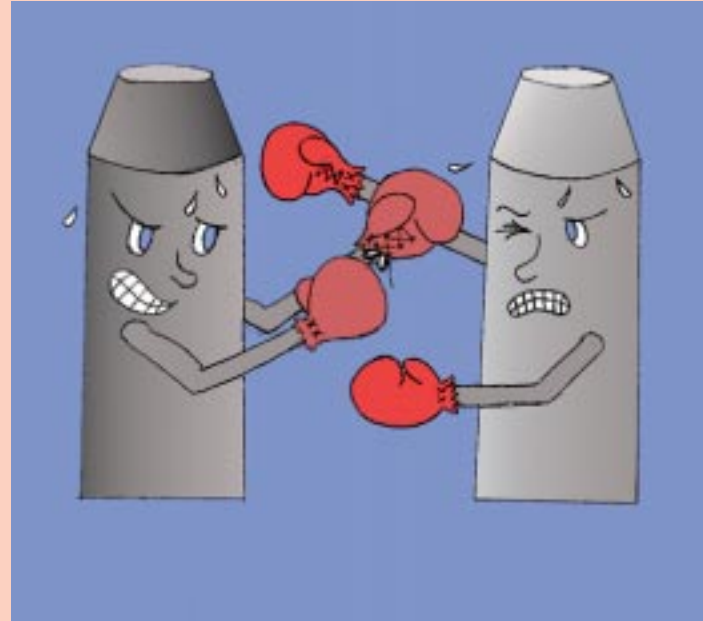
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DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

MECHANICAL DESIGN

» LAYOUT ISSUES

- **The pin fights**
 - **Why we need alignment pins**
 - **PCC**
 - **Probe card carrier - to insert ring**
 - **Pogo stack - to same pin in insert ring**
 - **Load board/ stiffener to same pin in insert ring**
 - **Non-PCC**
 - **Probe Card/ stiffener to pogo stack**
 - **Load board to same pin in pogo stack**



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MECHANICAL DESIGN

» LAYOUT ISSUES

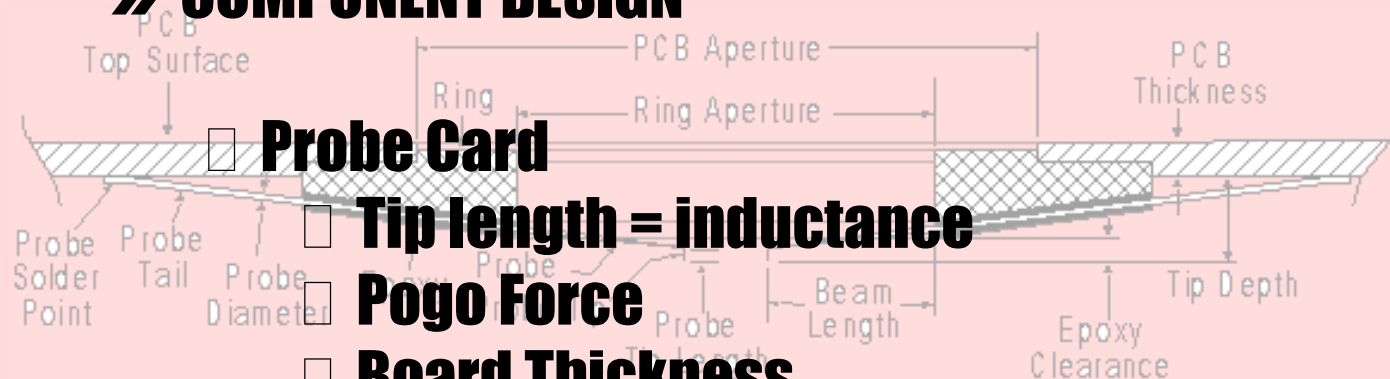
- Design from the bottom up**
 - Prober top plate (ring carrier)**
 - Probers optimal probing height**
 - Probe tip depth (minimize)**
 - Probe card thickness**
 - Minimum load board height (from top plate)**
 - Choose pogo pin**



DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

MECHANICAL DESIGN

» COMPONENT DESIGN



Probe Card

Tip length = inductance

Pogo Force

Board Thickness

Stiffener requirements - top and bottom

FEA to determine deflection



MECHANICAL DESIGN

» COMPONENT DESIGN

- **Pogo Stack**
 - **Housing should be metal**
 - **Other materials driven by design of signal transmission**
 - **Provide pogo overdrive features**
 - **Pogo's easily removable**
 - **Flange mount for probers with PCC's**
 - **Cam followers for clamp mount for probers without PCC's**



MECHANICAL DESIGN

» COMPONENT DESIGN

- Load Board**
 - Provide stiffener**
 - Mount stiffener directly to test head**
 - Float load board**
 - Do not bolt load board to pogo stack**
 - Make sure 'z' height sufficient for devices**



PROJECT MANAGEMENT

- » ASSUME LEADERSHIP ROLE**
- » PROJECT MANAGER/TEAM**
- » CONCURRENT DEVELOPMENT**
- » GANTT CHARTS**
- » DESIGN REVIEWS W/CUSTOMER**



DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION



INTEGRATION

- » INSTALLATION
- » FUNCTIONAL TESTING
- » DEBUG

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INSTALLATION

» INSTALL

- Docking** **1**
- Insert / Clamp Ring** **2**
- Probe Card** **3**
- Pogo Stack** **5**
- Load Board** **8**

» FIT CHECK

- Probe card loading** **4**
- Probe card to Pogo Stack** **6**
- Pogo Stack to Load Board** **9**

» CALIBRATE

- Probe Card to Pogo Stack** **7**
- Pogo Stack F.A. to Docking R.A.** **10**
- Docking R.A. to Test Head** **11**



DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

FUNCTIONAL TESTING

- » **SHORT OUT SIGNALS ON PROBE CARD**
- » **WRITE OPENS/SHORTS TEST - ASSIGN CHANNELS**
- » **PERFORM TEST**
- » **EVERYTHING IS PERFECT RIGHT?**



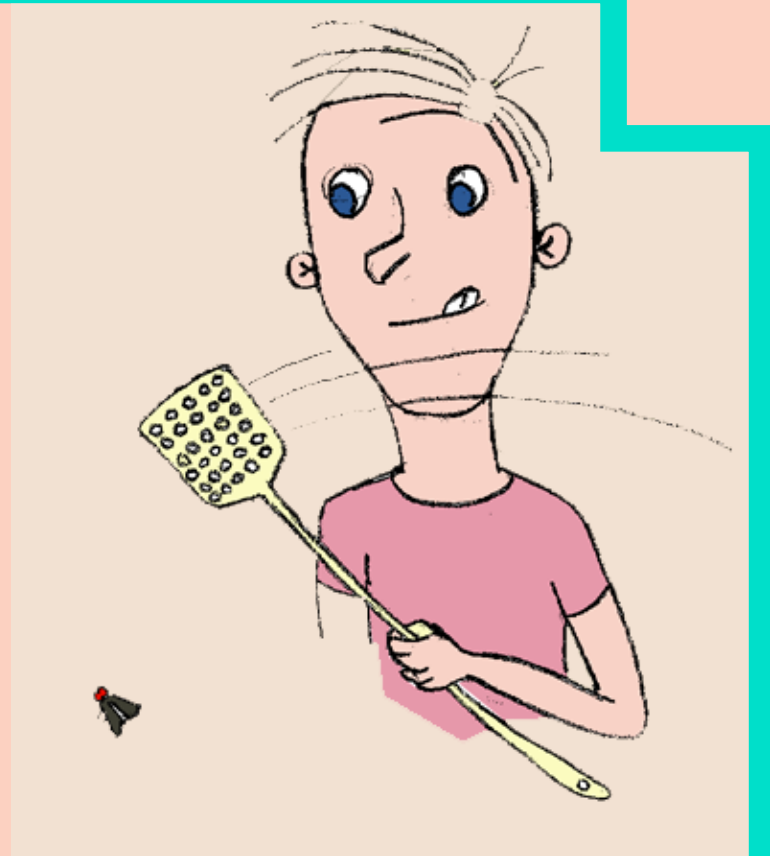
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DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

DEBUG

LEVEL 1 DEBUG: VERIFY CHANNELS AND CHECK FOR THE OBVIOUS

- » ON PROBE CARD: OHM OUT
POGO PIN PAD/VIA TO
PROBE LAND
- » TEFLON TAPE ON POGO
PAD/VIAS
- » OHM OUT LOAD BOARD PAD FOR TEST HEAD OUTPUT TO
PROBE LAND
- » TEFLON TAPE ON LOAD BOARD (BOTH SIDES?)



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DEBUG

LEVEL 2 DEBUG: 'Z' HEIGHT ISSUES

- » **VERIFY FLAT MOUNTING SURFACE FOR POGO STACK**
- » **VERIFY HEIGHT OF POGO (TOP AND BOTTOM) FROM MOUNTING SURFACE**
- » **VERIFY PROBE CARD MOUNTING SURFACE**
- » **VERIFY 'Z' HEIGHT REPEATABILITY OF PROBE CARD LOAD**
- » **OHM OUT POGO PIN**
- » **VERIFY 'Z' HEIGHT ON DOCKING VS. PRINTS**



DESIGN CONCEPTS FOR A TOTAL INTEGRATED SOLUTION

DEBUG

LEVEL 3 DEBUG: ITS AN 'X' 'Y' THING

» REMOVE PROBE CARD AND

POGO STACK: ✓ ✓ FIT

» ALIGNMENT PINS- P.C. CARRIER
-TO-CHANGER CLAMP &
PROBE CARD-TO-POGO STACK?

» ALIGNMENT PINS: P.C. CARRIER
-TO-CHANGER CLAMP &
POGO STACK-TO-INSERT RING
/RING CARRIER?



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SUMMARY

» **TAKE CONTROL**

» **DRIVE THE SYSTEM CONCEPT AND SPECIFICATION**

» **ESTABLISH AND MAINTAIN STRUCTURED COMMUNICATION**

» **ONLY DO BUSINESS WITH AN INTEGRATOR**

